LIST 12 (See S.No. 187 of the Table)

(1) LSI / VLSI tester

(2) Micromanipulators

(3) Molecular beam expitaxy system (MBE system)

(4) Expitaxial reactors

(5) Chemical vapour deposition (CVD) system - Low pressure CVD (LP CVD) - Metal organic CVD (MO CVD)

(6) High pressure oxidation systems

(7) Chemical etching systems

(8) Plasma etchers

(9) Reactive ion beam etchers (RIBE)

(10) Reactive ion etchers

(11) RF sputtering systems

(12) Direct digital control furnaces

(13) Ion-implanters (low/ medium / high current)

(14) Lithography systems

(15) Direct step on wafers / steppers

(16) X-ray lithography systems

(17) E-Beam mask making system

(18) E-Beam direct write system

(19) Mask aligners

(20) Mask inspection systems (comparators)

(21) Tape automated bounders

(22) Laser zappers

(23) Wafer recognition wire bonders

(24) Wafer scriber or Wafer slicer or Wafer sawing machine or Wafer fractures or any combination thereof

(25) Die bonders or wire bonders or combination thereof

(26) Wafer sawing machine; Wafer prober

(27) Leak detection system

(28) Clean room air showers

(29) Particle monitor / counter both air and liquid borne

(30) Automatic encapsulation system; Automatic marking / branding machine

(31) Clean room laminar flow air handling system

(32) Ultra clean room equipment

(33) Ultra high purity demineralised water treatment plant

(34) PVDF welding and orbital welding machines

(35) Ultra high pure (UHP) gas distribution system

(36) Toxic gas distribution / monitoring system